

TIRUCHIRAPPALLI - 620 015

DEPARTMENT OF ECE

NOTICE INVITING QUOTATION

File No.	NITT/F.NO.021/CAPEX/2022-23/ECE	Date:	06.03.2023
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То

(Supplier Address)

Sealed quotations are invited from reputed Authorized Dealers / manufacturers for the supply of the Items.

Name of the Item			Supply & Installation of Boards (Faculty
			Name Boards, Dept. Name Boards etc.
			for NBA)
Qua	antity Required	:	Mentioned in Technical specs
Spe	cification	:	(As per enclosed Schedule Annexure – I)
1.	1. Quotation Reference No.		NITT/F.NO.021/CAPEX/2022-23/ECE
2.	Last date and Time for receipt of	•	20.03.2023 before 11 00 AM
	quotation		
3.	Date & Time of opening of	:	21.03.2023 at 02.00 PM
	Quotation		
4.	EMD Amount	:	
			Rs, 5,000/- (2%)
5.	Validity (Days)	:	90 Days
6.	Address to which quotations are	•••	The Director,
	to be sent		National Institute of Technology,
			Tiruchirappalli – 620 015, Tamil Nadu,
			India
Kind attention to			Dr. Murali Krishna
	Phone	:	0431 250 3310
	E-mail	:	eceoffice@nitt.edu, mkr@nitt.edu

1. Quotations should be submitted in the format given in Annexure - I and Annexure-II

2. The envelope should contain the following details:

"QUOTATION AGAINST ENQUIRY" Supply & Installation of Boards (Faculty Name Boards, Dept. Name Boards etc. for

NBA)NITT/F.NO.021/CAPEX/2022-23/ECE

Kind attention to: Dr. Murali Krishna

Last date and Time for receipt of quotation: 20.03.2023 before 11 00 AM



Terms and Conditions:

1.	The quotation must be in the format furnished by NIT Tiruchirappalli and should
	be free from corrections/erasures. In case there is any unavoidable correction it
	should be properly attested. If not, the quotation will not be considered.
2	Earpost Monoy Doposit (EMD) is to be submitted by way of Domand Draft
۷.	drawn on any Nationalized bank in India in favor of "The Director NIT
	Tiruchirappalli" payable at Trichy The bids submitted without FMD will be
	treated as non-responsive and will be rejected. EMD shall bear no interest.
	Bidder must fill the EMD returning Form (Annexure-III) and submit along with
	the quotation. EMD amount of Rs, 5,000/- (2%) of estimate value is applicable,
	however UDYAM & NSIC registered Micro & small enterprises are exempted
	as per Govt.norms proof to be attached.
3.	You are invited to submit your most competitive quotation for the supply of
	goods according to the specifications and delivery terms as given. Bank
	guarantee submitted for EMD shall be valid for 45 days beyond bid validity
Δ	Bidders may send the quotations in sealed covers with the quotation reference
ч.	number and last date for receipt of quotations duly superscribed on the cover
	Kind Attention to: as mentioned in the point No. 6
	NB: Mention the company Contact Number / E-mail id on the cover.
5.	Quotation will be opened on due date at 21.03.2023 at 02.00 PM at the Store
	and Purchase Section, NIT, Tiruchirappalli in presence of the tenderers or
	their representatives who may wish to be present.
	(Any change in the date, time and venue of the quotation opening will be
6	The National Institute of Technology Tiruchirappalli reserves the right to
0.	accept or reject any guotations, and to cancel the bidding process, and reject
	all quotations at any time prior to the award of order without assigning any
	specific reason thereof.
7.	Manufacturer's name and country of origin of materials offered must be clearly
	specified. Printed brochures, Purchase preference is only for Micro & Small
	enterprises (MSE's) register in UDYAM Portal or NSIC as per Ministries policy
8	Samples must be submitted where specified along with the quotations. Samples
0.	must be carefully packed sealed and labelled clearly with enquiry number
	subject and sender's name for easy identification. Rejected samples will be
	returned at your cost if insisted
9.	All supplies are subject to inspection and approval before acceptance.
	Manufacturer / supplier warranty certificates and manufacturer / Government
	approved lab test certificate shall be furnished along with the supply, wherever
10	applicable
10.	quantity specified in this enquiry
11.	Startup company exempted from prior turnover & prior experience (startup
	certificate registered with DIPP should be enclosed)
12.	The bidder has to submit the bids in sealed envelope, (separate for each tender).
	Further Bidder should not send clubbing many tenders in one envelope, in such
	case all the bids will be rejected.



13.	Bid Price
	a. The contract shall be for the full quantity Bidders must quote for entire quantity. Each bidder shall submit only one quotation in Indian Rupee only.
	 b. Post work orders & completion certificate should be submitted, wherever applicable.
	c. The rates quoted by the bidder shall be fixed for the duration of the contract and shall not be subject to adjustment on any account.
	d. GST, packing, forwarding and delivering other allied items at the destination shall be included in the price. All such price components may be shown in the quotation. If there is no indication regarding above charges. It will be considered as inclusive of all charges.
	e. If any arithmetic mistake in total / GST calculation is observed, the same shall be corrected by the purchaser with an intimation to bidder
	f. In case the items in the enquiry are covered by any rate contract or any other state or central Government, it should be specified in your quotation and accepted contract rates should also be mentioned. It should be confirmed whether you could supply at the RC rates outside rate contract
	g. Quotations containing conditions like "subject to prior sale" may not be considered.
	 Delivery period required for supplying the material should be invariably specified in the quotation
	 Bids without quoting GST (unless exempted) will be treated as invalid & disqualified.
	j. If there is a discrepancy between unit price and total price, the unit price will be considered. If there is any mismatch between figure and word, the amount in word shall prevail.
14.	Evaluation of quotations: Quotations will be evaluated item-wise or lump sum basis. The purchase committee will evaluate and compare the quotations determined to be substantially responsive i.e. (i) are properly signed; (ii) Conform to the terms & conditions and specifications; and (iii) price offered are competitive.
15.	Award of contract
	a. The National Institute of Technology, Tiruchirappalli will award the Order for supply of Goods / Services to the bidder whose quotation has been determined to be substantially responsive, and who has offered the lowest evaluated quotation price.
	 b. The Bidder should furnish the contract agreement and performance security within 15 days from the date of receipt of the order for supply of goods / services, failing which the order will be cancelled without further notice and awarded to next eligible bidder.
	c. Notwithstanding the above, National Institute of Technology, Tiruchirappalli reserves the right to accept or reject any quotations, and to cancel the bidding process, and reject all quotations at any time prior to the award of order without assigning any specific reason thereof.
	d. National Institute of Technology, Tiruchirappalli, prior to the expiration of the quotation validity period, will notify the bidder whose bid is accepted for the award of contract. The terms of accepted offer shall be incorporated in the purchase order.
16.	Warranty: 12 Months shall be applicable to the supplied goods and installation
	work. Bidder should clearly indicate the arrangements for support and
	maintenance during the period for which the warranty shall be in force.
17.	Performance Security: 3 %



18.	Payment: 100% will be paid after Installation and satisfactory working/date of completion of service if the documents are in order. The bill should be raised in favor of "The Director, National Institute of Technology, Tiruchirappalli, Tamil Nadu, India." with institute GST No. 33AAATN5491Q1ZZ.No advance will be provided to the supplier and installer.
19.	Liquidity damages If the bidder / supplier, after accepting the Purchase Order or supply of Goods / Services, fails to deliver any or all of the Goods or to perform Services within the period(s) specified in the Order, The National Institute of Technology, Tiruchirappalli shall impose penalty without assigning any reasons to the bidder / supplier a sum equivalent to 0.50 % of the total cost as indicated in the Purchase Order (which will be deemed as agreed price) for each week or part thereof of delay until actual delivery or performance is completed and such penal charges shall be limited to a maximum of 5% of the agreed price. Once the maximum is reached The National Institute of Technology, Tiruchirappalli, may proceed on its own to consider the termination / cancellation of the Order and may inform the bidder about the cancellation of the said purchase order. unless extension is obtained in writing from the office / Department on valid ground before expiry of delivery period
20.	If the deliveries are not maintained and due to that account Procuring Entity is forced to buy the material at your risk and cost from elsewhere, the loss or damage that may be sustained there by will be recovered from the defaulting supplier
21.	Dispute clause: Any dispute relating to the Enquiring /Tender of the indented item shall be under the Hon'ble Court having its jurisdiction over Tiruchirappalli only
22.	Startup company exempted from Prior Turnover & Prior Experience (Startup certificate registered with DIPP should be enclosed)
23.	GST as applicable
24.	Performance Bank guarantee should be valid for 60 days beyond the guarantee & warranty and the BG submitted for EMD shall be valid for 45 days beyond bid validity period.
25.	Bids submitted without EMD (unless exempted) will be treated as disqualified.
26.	The successful bidder should submit Security Deposit/PBG within 15 days from the date of placement of order. The EMD shall be returned only after receipt of SD. If the bidder fails to deliver the material, then the EMD/SD shall be forfeited.



Special Terms & Conditions

The Finalization of tender shall be made on GroupWise lowest basis (I,e Group 1: Foam Boards , Group 2: Acrylic Boards, Group 3: Reflector Based AI Boards) Note 1: The bidders should quote as per the specification as given in the tender failing which the tender will be liable for rejection.

Note 2: The quantity may vary at exceptional circumstances.

Note 3: The bidders may quote from any one of the group (i,e Group 1/Group 2/ Group3) also or all the groups. L1 will be decided based on group wise individually. Note 4: The Colour of the boards will be mostly, White board with sticker in the blue colour or as applicable.

I/We hereby certify that I/We shall abide hereby the terms and conditions and the Annexures of this limited quotation.

Signature & Seal of Vendor with Date

For any details / clarifications regarding could be obtained from Stores and Purchase Section on all working days during 10 AM to 5 PM.

For further detail related to Technical specifications kindly contact Dr. Murali Krishna

(Purchase initiator), **DEPARTMENT OF ECE NITT/F.NO.021/CAPEX/2022-23/ECE**, <u>eceoffice@nitt.edu</u>, mkr@nitt.edu, 0431 250 3310.



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(NB: Mention the Contact Number / E-mail on the cover. Any change in the date, time and venue of the tender opening will be informed to the bidders through telephone / E-mail)

Enclosures: 1) Specifications	of the equipment	Annexure – I
	, opeenieaaene	or and organprinerite	

2) Price Format Annexure - II

3) EMD Return Format Annexure – III

4) Bank Mandate Form Annexure – IV

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Annexure- I

Specifications of the Equipment

Ref: NITT/F.NO.021/CAPEX/2022-23/ECE

Date:06.03.2023

S. No	Specification		of	NIT-T	Specification of the Supplier
	Note: The Col	our of the boards will be mo	stly, White board with	n sticker in the	
	blue colour or	as applicable.			
	S. No	Board Type	Dimension	Quantity	
		Group 1: Foa	m Boards		
	1.	Foam Board (Dept. & Institute Vision & Mission)	3.5 Feet x 3 Feet	04	
		3mm Thickness			
	2.	PEO's) 3mm Thickness	3.5 Feet x 3 Feet	06	
	3.	Foam Board (Dept. PSO's)	3.5 Feet x 3 Feet	02	
		3mm Thickness			



4.	Foam Board (Dept. PO's	6 Feet x 4 Feet	06	
	3mm Thickness			
5.	Foam Board (Miscellaneous)	18 Inch x 3 Inch	42	
	3mm Thickness			
6.	Foam Board (No Cell Phone Use with symbols)	18 Inch x 4 Inch	12	
	3mm Thickness			
7.	Foam Board (Do's and Don'ts)	4 Feet x2.5 Feet	12	
	3mm Thickness			
8.	Foam Board (Two- Wheeler, Car Parking.)	18 Inch x 6 Inch	06	
	3mm Thickness			
9.	Foam Board (UPS, Store room & Power Room.)	18 Inch x 5 Inch	25	
	3mm Thickness			
10.	Foam Board (Office Working Hours, Rooms No's with arrow symbols)	2 Feet x 1.5 Feet	04	
	3mm Thickness			
11.	Foam Board (Emergency Number)	2 Feet x 1.5 Feet	12	
	3mm Thickness			
12.	Foam Board (Rest Rooms with directional sign Board)	24 Inch x 6 Inch	06	
	3mm Thickness			



13.	Foam Board (List of Laboratories)	5 Feet x 3 Feet	01	
14.	Foam Board (Lab-in- Charge etc.) 3mm Thickness	18 Inch x 8 Inch	13	
15.	Foam Board (PI Project) 3mm Thickness	8 Feet x 4 Feet	02	
16.	Foam Board (List of Equipment's details etc.) 3mm Thickness	4 Feet x 3 Feet	13	
17.	Foam Board (List of HODs) 3mm Thickness	3 Feet x 2 Feet	01	
18.	Foam Board (Lab name in 3 Languages) 3mm Thickness	5 Feet x 2 Feet	12	
19.	Foam Board (Room Number) 3mm Thickness	6 Inch x 4 Inch	70	
20.	Foam Board (Dept. Name) 3mm Thickness	15 Feet x 2 Feet	01	
21.	Foam Board (Dept. PhD Scholars Details) 3mm Thickness	4 Feet x 3 Feet	01	
	Group 2: Acry	lic Boards		
22.	Acrylic Base Board (Faculty Detail Main Slot Board) 3mm Thickness	7 Feet x 4 Feet	01	



		23.	Acrylic Board (Slot Fixing Faculty Name type) 3mm Thickness	24 Inch x 2 Inch	60	
		24.	Acrylic Hanging Board (Faculty Name in rooms)	20 Inch x 5 Inch	40	
		25.	Acrylic Board with Frame (Dept. Name) 3mm Thickness	15 Feet x 4 Feet	01	
		26.	Acrylic Engraving Board (Garden related board etc.)	2 Feet x 1 Feet	03	
			Sinin Thickness			
			Group 3: Reflector I	Based Al Boards		
		27.	Reflector based Al Board (Welcome to Dept. Board) 3mm Thickness	5 Feet x 2.5 Feet	02	
				1	11	
Reasons	(if there	is diffor	ence in specification)			
1.			onve in specification			
2.						



SCOPE OF WORK

Note 1: The Contents are tentative in nature. There may be a possibility of increase/Variation in content at the time of printing on the boards based on the needs.

Note 2: The sample contents of one lab had been mentioned in BoQ 7, BoQ 13, BoQ 14, BoQ 16, BoQ 18 in this document. This may vary as per the lab requirement

Note 3: The Content for room numbers in ground floor had been mentioned for sample purpose in BoQ 19 in this document. This may vary for other floors

Note 4: The Content for faculty name in rooms had been mentioned for sample purpose in BoQ 24 in this document. It will vary as per the rooms

BoQ 1 : Thickness 3 mm & Dimension 3.5 Feet x 3 Feet

Institute Vision --- Note: 04 No's are required

To provide valuable resources for industry and society through excellence in technical education and research

Institute Mission

To offer state-of-the-art undergraduate, postgraduate and doctoral programmes

To generate new knowledge by engaging in cutting-edge research

To undertake collaborative projects with academia and industries.

To develop the human intellectual capability to its fullest potential

Department of Electronics and Communication Engineering

Vision

 \bullet To excel in education and research in Electronics and Communication Engineering

Mission

- To educate with the state of art technologies to meet the growing challenges of the industry.
- To carry out research through constant interaction with research organizations and industry.
- To equip the students with strong foundations to enable them for continuing Education

BoQ 2 : Thickness 3 mm & Dimension 3.5 Feet x 3 Feet

Department of Electronics and Communication Engineering --- Note: 06 No's are required **Program Educational Objectives (PEOs)**

- PEO1: Our Graduates would be successful in Technical and Professional careers
- PEO2: Our Graduates would be successful in their post-undergraduate studies at leading Institutions

Department of Electronics and Communication Engineering

M Tech Communication Systems

Program Educational Objectives (PEOs)

• PEO1: Graduates of the programme will be professional Telecommunication Engineers, Researchers, and Academicians with ethical and societal responsibility.

• PEO2: Graduates of the programme, as part of an organization, will continue to learn and handle cutting-edge technology.

Department of Electronics and Communication Engineering M Tech (VLSI Systems)

Program Educational Objectives (PEOs)

• PEO1: Graduates will be successful in facing the challenges in their professional career in industry, government and academia by integrating the existing and advanced knowledge in VLSI Systems to solve complex problems in Electronics and Communication engineering.



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• PEO2: Graduates will be efficient in adapting new technologies, achieve excellence in their professional career, lead research as well as development projects/activities and establish themselves as successful professional.

• PEO3: Graduates will practice and inspire high ethical and technical standards, possess technical competency in VLSI Systems and take up higher studies.

BoQ 3: Thickness 3 mm & Dimension 3.5 Feet x 3 Feet

Program Specific Outcome ---- Note: 02 No's are required

- To face the challenges in their professional career in industry and government by integrating the existing and advanced knowledge in Electronics and Communication engineering to analyses problems and provide solutions.
- To design cost-effective systems and components for engineering/social applications by applying appropriate technology in Electronics and Communication engineering domain.
- To lead research and transform innovative ideas into reality, establish themselves as successful professionals and possess technical competency to take up higher studies.

BoQ 4: Thickness 3 mm & Dimension 6 Feet x 4 Feet

Department of Electronics and Communication Engineering --- Note: 06 No's are required **Program Outcomes (POs)**

Graduates of the Electronics and Communication Engineering programme will have the ability • PO1: To apply the knowledge on Mathematics, Science, and Engineering concepts in Complex Engineering problems..

• PO2: To analyse the complex engineering problems by using the first principles of Mathematics and Engineering fundamentals.

• PO3: To design a component, a system or process to meet the specific needs within realistic constraints such as economics, environment, ethics, health, safety and manufacturability.

• PO4: To perform investigations, design as well as conduct experiments, analyse and interpret the results to provide valid conclusions.

• PO5: To select and apply appropriate techniques for the design & analysis of systems using modern CAD tools.

• PO6: To offer engineering solutions to societal problems.

• PO7: To understand that the solutions have to be provided taking the environmental issues and sustainability into consideration.

• PO8: To understand professional responsibilities and Ethics.

• PO9: To function effectively either as a member or a leader in multidisciplinary activities.

• PO10: To communicate effectively to both the peers and the others and give as well receive clear instructions.

• PO11: To apply engineering & management principles in their own / team projects in a multidisciplinary environment.

• PO12: Realize the need for lifelong learning and engage them to adopt technological changes

Department of Electronics and Communication Engineering M Tech (Communication Systems) Program Outcomes (POs)

• PO1: Postgraduates of the Communication Engineering programme will demonstrate deep knowledge with an ability to discriminate, evaluate, analyze and synthesize existing and new knowledge in telecommunication engineering and the related mathematics.

• PO2: Postgraduate either as an individual or in the group, will have the ability to define the problems and provide solutions by designing and conducting experiments, interpreting and analyzing data, and reporting the results.

• PO3: Postgraduates will have the confidence to apply engineering solutions in global and societal contexts to contribute to the community for the sustainable development of society

• PO4: Postgraduates will demonstrate the ability to design optimal telecommunication systems that would encompass signal processing, modulation schemes, channel selection, and antenna design and would meet specifications and requirements after considering the related factors in the core area of expertise.

• PO5: Postgraduates will demonstrate the ability to create, select, learn and apply the appropriate software to solve telecommunication engineering problems.



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• PO6: Postgraduates will have the ability to participate as members of telecommunication engineering society and members of multidisciplinary teams to demonstrate a capacity for self-management and teamwork to achieve the common goal

• PO7: Postgraduates will understand the role of economic and financial factors in developing products in the field of telecommunication.

• PO8: Postgraduates will be able to communicate well with the engineering community in both verbal and writing regarding complex engineering activities confidently and effectively.

• PO9: Postgraduate will understand the rapid advances in telecommunication systems, recognize the need for lifelong learning and improve knowledge continuously.

• PO10: Postgraduates will be broadly educated and will have an understanding of the impact of research outcomes, professional practices, and on society and demonstrate ethics in performing research and publishing the technical documents.

• PO11: Postgraduates should be capable of self-education and clearly understand the value of achieving perfection by learning by mistakes without depending on external feedback.

Department of Electronics and Communication Engineering M Tech (VLSI Systems) Program Outcomes (POs)

• PO1: To acquire in-depth knowledge in Embedded System, Digital VLSI and Mixed Signal Systems including wider and global perspective, with an ability to discriminate, evaluate, analyse and synthesise existing and new knowledge, and integration of the same for enhancement of knowledge.

• PO2: To design and analyse complex VLSI/Embedded circuits critically, using appropriate analytical methods as well as front end and back end tools including prediction and modelling at industry standards with an understanding of the limitations.

• PO3: An ability to independently carry out research /investigation and development work to solve practical problems and have the preparedness for lifelong learning.

• PO4: To comprehend and write effective reports and design documentation by adhering to appropriate standards, make effective presentations, and give and receive clear instructions.

• PO5: Students should be able to demonstrate a degree of mastery in VLSI/Embedded system by way of developing new algorithms, techniques, solutions to domestic and industrial problems.

• PO6: To acquire professional code of conduct, ethics of research and scholarship, consideration of the impact of research outcomes on professional practices and an understanding of responsibility to contribute to the community for sustainable development of society.

BoQ 5: Thickness 3 mm & Dimension 18 Inch x 3 Inch

Zero tolerance for Sexual Harassment -- Note: 3 No's are required

Say NO to RAGGING --- Note: 3 No's are required

Save Energy: -- Note: 12 No's are required Please Switch off A/Cs, Fans & Lights when not in use.

LEAVE YOUR BAGS HERE -- Note: 12 No's are required

LEAVE YOUR FOOTWEAR HERE --- Note: 12 No's are required



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BoQ 6: Thickness 3 mm & Dimension 18 Inch x 4 Inch



Note: 12 No's are required

BoQ 7: Thickness 3 mm & Dimension 4 Feet x 2.5 Feet

Dos and Don'ts in Laboratory - Note: 12 No's are required

Do not handle any equipment before reading the instructions /Instruction manuals.

- 1. Read carefully the power ratings of the equipment before switching ON.
- 2. Observe type of equipment power sockets to avoid mechanical damage.
- 3. Do not forcefully place connectors to avoid the damage.
- 4. Strictly observe the instructions given by the Teacher/ Lab Instructor.
- 5. Submission related to whatever lab work has been completed should be done during the next lab session.
- 6. Students should switch on the power supply only after getting the circuit checked by the lab assistant / teacher.
- 7. After the experiment is over, the students must hand over the components, circuit board, wires etc. to the lab assistant/teacher.

Note: The Contents in each lab may vary

BoQ 8: Thickness 3 mm & Dimension 18 Inch x 6 Inch

Two Wheelers Parking --- Note: 4 No's are required **Car Parking** ---- Note: 2 No's are required

BoQ 9: Thickness 3 mm & Dimension 18 Inch x 5 Inch

UPS --- Note: 12 No's are required

Store Room ---- Note: 12 No's are required Power Room ---- Note: 1 No is required

BoQ 10: Thickness 3 mm & Dimension 2 Feet x 1.5 Feet

Office Working Hours -- Note: 1 No is required Morning: 8.30 A.M– 12.30 A.M Lunch: 12.30 P.M – 01.15 P.M Afternoon: 01.15P.M – 05.15 P.M

- Ground Floor Note: 1 No. is required
- 1. Room No: 101 109
- 2. Room No: 110 120

First Floor Note: 1 No. is required Room No: 201 – 210 Conference Room: 201

1. Room No: 211 – 220



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Second Floor Note: 1 No. is required

- 1. Room No: 301 310
- 2. Room No: 311 320

BoQ 11: Thickness 3 mm & Dimension 2 Feet x 1.5 Feet

FOR EMERGENCY	
HOD/ ECE	9486001109
Office/ ECE	(0431) 2503300
NITT hospital	(0431) 2503860
NITT ambulance	9486001162
Security	(0431) 2503900/9486001168/9500684272
Estate Maintenance	(0431) 2503830/9486001188
Anti-Ragging Helpline	9486001180
	ANTIRAGGING@NITT.EDU
Students Grievance helpline	9486001198
	STUDENTSGRIEVANCE@NITT.EDU
Women Sexual Harassment helpline	9486001150
	WOMENCELL@NITT.EDU
Lab in charge	

Note 12 No's are required

BoQ 12: Thickness 3 mm & Dimension 24 Inch x 6 Inch

Rest room

Note: 6 No's are required

BoQ 13: Thickness 3 mm & Dimension 5 Feet x 3 Feet

Laboratories Name	Room No
Pattern recognition and Computational intelligence	101
Computer Vision and Machine Learning Lab	102
Medical Image Computing & Artificial Intelligence Lab	103A
Signal Processing Research Laboratory	103B
Centre for Electronics System Design, Calibration and Testing (CESDeCT)	103C
Microwave Electronics Laboratory	104
Microwave Planar Antenna and Filter Design Research laboratory	105



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Electronic Devices and Integrated Circuit	106A
Engineering	
Devices and Networks Laboratory	106B
Artificial Intelligence Laboratory	107A
Analog VLSI and Embedded System Design Lab	107-В
Wireless Communication Laboratory	202A
Wireless network and simulation laboratory	202B
Wireless Communication & Signal	203
Processing Laboratory	
Smart Antenna Design Lab	204
Wireless Communication and Networks Research Laboratory	205
Fiber optic communication laboratory	206
Light wave Communications Research Laboratory	207
Digital Electronics Lab	208A
Communication Engineering Laboratory	208A
Photonics and Communication Research Laboratory	208B
Metamaterials Research Laboratory	209
Microwave Integrated Circuits Laboratory	210
Analog VLSI and Embedded System Design Lab	304
Centre for SoC Design and Fabrication	304C
Wireless System Design Lab.	305,306
Microprocessor and Microcontroller Laboratory	307
Digital Signal Processsing Laboratory	308A
RF CMOS IC Design Laboratory	308B
Signal and Image Processing Laboratory	309
RF and Wireless System Design Laboratory	CSE Block

Note: 1 No is required

BoQ 14: Thickness 3mm & Dimension 18 Inch x 8 Inch

Faculty In charge Dr M Bhaskar Staff In charge Mr A Kiran Kumar



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Note: The above Lab In charge Content is just an example it will change as per the lab for remaining 12 labs Note: 13 No's are required

Project Title	Funding (in Lakhs)	Funding Agency	Durati on (From-	PI &Co-PI
Centre for SoC Design and Fabrication	188.5	Mr. Raj Shanmugaraj Alumnus – 1979 Batch	2022- 2026	Dr. G. Lakshminarayanan Head Members: Dr.P.Muthuchidambaranathan Dr.M.Bhaskar Dr.B.Rebekka Dr.R.Thilagavathy Dr.R.K.Kavitha Dr.Varun P.Gopi
Design of Digital Signal Processor using SCL foundry	12.8	RESPOND, ISRO-STIC	2021- 2023	Dr. G. Lakshminarayanan
Machine Learning/Artificial Intelligence (ML/AI) Hardware/Software Framework for Vyomnoids	49.55	Indian Space Research Organisation (ISRO)	2022- 2025	Dr. Varun P. Gopi Dr G. Lakshminarayanan
Design and Implementation of MB- OFDM UWB Transceiver Modules using Asynchronous Pipelining	33.5	MeitY	2008 - 2011	Dr. G. Lakshminarayanan Dr.B.Venkataramani
Deep Learning-Based Reconfigurable and Multifunctional Nanophotonic Interconnects for Hyperscale Data Centers and 6G Backhaul Networks	25.13	CRG, SERB- DST	2022- 2025	Dr. G. Thavasi Raja Dr. D. Sriram Kumar
Orthogonal Time Frequency Space Modulation based Index Modulation for 6G Communication Systems	16.06	SERB	2022- 2024	Dr. P. Maheswaran
Self-Energised UAV-assisted Communications for 5G Wireless Networks	73.23	MHRD- SPARC	2019- 2023	Dr.P.Muthuchidambaranathan Dr.G.Lakshminarayanan Dr.G.Thavasi Raja
Efficient Modulation Format Recognition and Optical Performance Monitoring for Intelligent Management of Future Optical Communication Networks	50.21	SERB, DST	2019 - 2023	Dr. R.K. Jeyachitra
Design and development of MIMO- GFDM systems for 5G eMBB services	20.88	SERB, DST	2019 - 2023	Dr.V.Sudha

BoQ 15: Thickness 3mm & Dimension 8 Feet x 4 Feet



Design of Substrate Integrated Waveguide Band Pass Filter for Ku Band Applications	10.32	CSIR-HRDG (Extra Mural Research Division) – SRF Direct category	2021- 2023	- Dr.N.Gunavathi (Project Supervisor)
Performance Analysis of Reconfigurable Intelligent Surfaces in High Altitude Platform Stations with Orthogonal Time Frequency and Space	10	SEED Grant, NIT-Trichy	2021- 2023	Dr. P. Maheswaran Dr. P. Sudharsan
Design and Development of Low- Cost Planar Broadband Antennas	4.4	SEED Grant, NIT-Trichy	2021- 2023	Dr. Hemant Kumar
Design and Development of Ferrite Dielectric Based Microstrip Isolator for X –Band Application	32.09	ISRO	2021- 2023	Dr. S S Karthikeyan Dr N.Gunavathi
Hunting representative sensors and constructing regression model between sensor outcomes using ML	19,82,06 8	DRDO,GTRE	4-02- 2021 to 3-8- 2022	Dr.E.S.Gopi
LC Band Pass Filter for Space Technology	48.44	ISRO (Space Technology Incubation Center)	2021- 2022	Dr. S S Karthikeyan Dr.N.Gunavathi
Networked airborne base stations for disaster management	10.8	DST	15.06. 2017 to 15.06. 2020	Dr.P.Muthuchidambaranathan
4D Trajectory-based Air Traffic Flow Management System using System Wide Information Management (4DADFMS)	11.5	Airport Authority of India	2020- 2022	Dr. P. Palanisamy Dr. varun P. Gopi
Analysis of aerial intelligent reflecting surfaces for application in 6G wireless systems	10	Shastri Indo Canadian Institute (SICI)	2020- 2022	Dr.P.Sudharsan
Algorithmic Approach to Achieve Maximum Functional Coverage Using Constrained Random Verification Platform (Consultancy Project)	2.7	MAXVY Technologies Pvt Ltd, Bangalore	2020 - 2022	Dr. G. Lakshminarayanan
Management of entities in a distributed NFV marketplace using Blockchain	6	INTEL	2018- 2019	Dr B.Malarkodi Dr.B.Rebekka Dr N.Gunavathi
Development of Dense Deployable MassiveMIMO antenna systems for5G Wireless Communications with reduced correlation / Mutual Coupling	21.74	DST – SERB	2019- 2022	Dr D Sriram kumar Dr P Gunavathi



Performance Analysis and Characterization of Si/ZnO Heterojunction diode as Pressure Sensor	18.30	TARE – SERB	2019- 2022	Dr D Sriram Kumar
Design and development of a dual band RF Energy Harvester for WirelessSensor Networks using AerosolJetting Technology	53.06	DST- IMPRINT	2019- 2022	Dr S S Karthikeyan
Development of 3Dprinted Wearable Button Antenna for SoldierPerformance Monitoring Applications	50.53	DST- IMPRINT	2019- 2022	Dr S S Karthikeyan
Development of Efficient Traffic Monitoring Analytics& Under Vehicle Scanning Inspection System	40.0	VANDI TECHNOLO GIES PTE LIMITED SINGAPORE	2019- 2022	Dr P Palanisamy Dr Varun P Gopi
Automated Prediction of Aizherimer's disease from Opltical Coherence Tomography Images of Retina using artificial Intelligence	19.48	SERB	2019- 2022	Dr Varun P Gopi
Metamaterial – Based Low ProfileLTCC Balanced Antipodal Vivaldi Antenna for 5G eMBB	48.6	SPARC- MHRD	2019- 2021	Dr R Pandeeswari Dr R Pandeeswari Dr V Sudha Dr S Deivalakshmi
Design and Development of X-band & Ka-band Passive Device	16.15	ISRO- STIC	2020- 2023	Dr.R.Pandeeswari Dr. S. Deivalakshmi Dr G Thavasi Raja Dr S S Karthikeyan
Self-Energised UAV-assisted Communications for 5G Wireless Networks	73.23	SPARC- MHRD	2019- 2021	Dr P Muthuchidambaranathan Dr G Lakshminarayanan Dr G Thavasi Raja
Adaptive Telemetry System for Launch Vehicle – demonstration of Proof of Concept	23.66	ISRO – RESPOND	2018- 2021	Dr G Lakshminarayanan
In depth investigation on corrosion and tribological studies on expandable engine	98.84	DRDO	2018- 2021	Dr G Lakshminarayanan
Energy efficient implementation of Multi-modular Exponential techniques for Public-key Cryptosystems	35.0	DST	2018- 2021	Dr G Lakshminarayanan
Management of entities in a distributedNFV market place usingBlockchain	6	INTEL	2018- 2019	Dr B Malarkodi Dr B Rebekka Dr N Gunavathi
Networked airborne base stations for disaster management	10.8	DST	2017- 2019	Dr P Muthuchidambaranathan
Highly Compact Very Large Mode- Area Hybrid Multi-Trench Optical	20.89	SERB	2017- 2020	Dr G Thavasi Raja Dr D Sriram Kumar



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Fiber for High-Power Industrial Lasing Applications				
Full Duplex and Cognitive Radio Architectures for Spectrally Efficient Communications	107	UGC – UKIERI	2017- 2020	Dr G Lakshminarayanan Dr B Venkataramani
Technology Incubation and Development of Enterpreneurs (TIDE) in the Areas of Electronics & ICT – CEDI	155	Deity	2015 – Till	Dr B Venkataramani Dr G Lakshminarayanan
Special Manpower Development Program for Chipsto System Design(SMDP-C2SD)	79.76	Meity	2014- 2019	Dr B Venkataramani Dr M Bhaskar Dr G Lakshminarayanan
Design & Implementation of Digital Modules of On Chip Speech Recognition System	-	Meity	2014- 2019	Dr G Lakshminarayanan
Wireless transceiver for low data rate applications (Institute Project)	-	Meity	2014- 2019	Dr M Bhaskar
Design & Implementation of baseband modules for wireless sensor networks	3.2	BROADCOM M FOUNDATIO N USA	2015- 2017	Dr B Venkataramani
Wireless System Design laboratory	60.0	FIST/DST	2012- 2017	Dr G Lakshminarayanan Dr P Muthuchidambaranathan Dr B Venkataramani
Low Complexity Energy efficient Transceiver for Cognitive Radio System	34.0	UKIERI	2012- 2014	Dr G Lakshminarayanan
Partner for the project on Rural and Remote Ubiquitous Broadband Wireless Access	34.0	UKIERI	2012- 2014	Dr G Lakshminarayanan
Design and Implementation of Low power analog front end modules for Wireless Sensor Networks	39.0	Deity	2012- 2015	Dr B Venkataramani Dr M Bhaskar
Embedded systems development using Intel atom 56XX processor	3.6	Intel- Bangalore	2011- 2012	Dr B Venkataramani

Note: 2 No's are required

BoQ 16: Thickness 3mm & Dimension 4 Feet x 3 Feet Sample Content --- Note: 13 No's are required

S.No	Equipments	Numbers	Funding agency	Approximate cost in Lakhs
1	New Port Fiber Optic Kit	03	Institute Plan Fund	12.0
2	Benchmark Optical Fiber Laboratory System	01	Institute Plan Fund	10.63
3	Photonics CAD version 1.6	05	TEQIP	3.64



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4	OPTSIM version 5.2	07	Institute Plan Fund	6.09
5	CRO	04	Institute Plan Fund	0.75
6	Function Generators	04	Institute Plan Fund	0.49
7	Computers	07	Institute Plan Fund	2.31
8	5KVA Online UPS	01	Institute Plan Fund	1.65
9	RSOFT CAD – Fullwave (GUI v2019.03)	03	Institute Plan Fund	7.49
10	Digital Communication trainer kit	01	Institute Plan Fund	1.78
11	Digital Storage Oscilloscope	02	TEQIP	1.24
12	Optical Spectrum Analyzer	01	TEQIP	16.58
13	Fiber optic workbench - Light Runner	01	Institute Plan Fund	8.61
14	Computers – Hp Prodesk	05	TEQIP	3.23
15	Avalanche Photodiode Module with Accessories	01	Institute Plan Fund	1.31
16	LED Module with Accessories	01	Institute Plan Fund	0.79

Note: The above Content will change for different labs

BoQ 17: Thickness 3mm & Dimension 3 Feet x 2 Feet

S.No	Name of the H.O.D	Year
1.	Dr P. Ramakrishna Rao	1982 - 1992
2.	Dr A.L. Abdulsattar	1992-1995
3.	Dr P Ramakrishna Rao	1995-1997
4.	Dr M J.S Rangachar	1997-1999
5.	Dr N Kalyanasundaram	1999-2007
6.	Dr B Vankataramani	2007-2010
7.	Prof P Somaskandan	2010-2013
8.	Dr D Sriram Kumar	May 2013 to August 2013 (incharge)
9.	Prof P. Somaskandan	September 2013 to January 2014
10.	Dr D Sriram Kumar	February 2014 to 2017



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11.	Dr G Lakshminarayanan	2017 to 2020
12.	Dr P Muthuchidambaranathan	2020 to 2022
13.	Dr M Bhaskar	2022 to till date

Note: 1 No. is required

BoQ 18: Thickness 3mm & Dimension 5 Feet x 2 Feet Fiber optic communication laboratory

ஃபைபர் ஆப்டிக் தொடர்பு ஆய்வகம்

फाइबर ऑप्टिक संचार प्रयोगशाला

- Note: The above Content will change for different labs Note: 12 No's are required
 - BoQ 19: Thickness 3mm & Dimension 6 Inch x 4 Inch

101, 102, 103A,103B,103C, 104 105 106A, 106B,107A,107B,110,111,112,113,114,115,116,117,118,119,120 etc Note: The above Content will change for floors Note: 70 No's are required

BoQ 20: Thickness 3mm & Dimension 15 Feet x 2 Feet Department of Electronics and Communication Engineering Note: 1 No. is required

No. of Scholars	No of Ongoing Ph.D.	No. of Completed	No. of Ongoing M.S.
Completed Ph.D. till	Scholars	M.S. Scholars	Scholars
date (Full time + Part time+ QIP)	(Full time + Part time + QIP)	(Full time + Part time+ QIP)	(Full time + Part time+ QIP)
79	93	26	4

Note: 1 No. is required

Acrylic Boards BoQ 22: Thickness 3mm & Dimension 7 Feet x 4 Feet BoQ 23: Thickness 3mm & Dimension 24 Inch x 2 Inch



NATIONAL INSTITUTE OF TECHNOLOGY TIRUCHIRAPPALLI - 620 015



DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING

NATIONAL INSTITUTE OF TECHNOLOGY, TIRUCHIRAPPALLI – 620 015

FACULTIES, TECHNICAL AND SUPPORTING STAFFS

Name	Room No.	Name	Room No.	Name	Room No.
Head of Department		Assistant Professors		Technical Staff	
Dr. M. Bhaskar	213	Dr. N. Gunavathi	221	Mrs. V Jeeva Stella	120
Department Office	212	Dr. Varun P. Gopi	320	Mr. R Sathik Batcha	114
Professors		Dr. R. Malmathanraj	317	Mr. P Viswanathan	
Dr. G. Lakshminarayanan	111	Dr. R. K. Kavitha	310	Mr. M Ramesh Babu	
Dr. P. Muthuchidambaranath an	312	Dr. R. Thilagavathy	311	Mr. A Kiran Kumar	308
Dr. M. Bhaskar	303	Dr. P. Maheswaran	110	Mr. B Raja Naik	104
Dr. D. Sriramkumar	214	Dr. P. Sudharsan	319	Mr. Bharat Bhushan Khare	107
Dr. P. Palanisamy	302	Dr. Hemant Kumar	216	Supporting Staff	
		Dr. Srinivasulu Jogi		Mr. P Sarvanan	212
Associate Professors		Dr. Bukke Chandrababu Naik		Mr. T Thangmuthu	212
Dr. B. Malarkodi	112	Dr. Bibin Francis		Others	
Dr. E. S. Gopi	101	Dr. Parthasarathy R		Dept. Library	301
Dr. R. Pandeeswari	119	Dr. Avik Hati		ECE. Association	217
Dr. R. K. Jeyachitra	215	Dr. B. Naresh Kumar Reddy		Conference Hall	201
Dr. B. Rebekka	220	Dr. Murali Krishna R		Meeting Room	113



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Dr. G. Thavasi Raja	118		Data Processing/ Staff room	
Dr. V. Sudha	211		FM Radio Station 90.8	
Dr. S. Deivalakshmi	117		Female Lounge	
Dr. S. S. Karthikeyan	314		C.C.S.	
			Mr. T Gopinath	
			Mr. D Kalaiselvan	
			Mr. R Senthil Kumar	

Note: The Designation of Non Teaching staff has to be added

BoQ 24: Thickness 3mm & Dimension 20 Inch x 5 Inch

Faculty Name Dr M Bhaskar Note: The name will change for different rooms Note: 40 No's are required

BoQ 25: Thickness 3mm & Dimension 15 feet x 4 Feet Department of Electronics and Communication Engineering --- Note: 01 No. is required

BoQ 26: Thickness 3mm & Dimension 2 Feet x 1 Feet

Tree Planted by

Dr B Venkataramani Note: The above content is a sample one. Note: 03 No's are required

BoQ 27: Thickness 3mm & Dimension 5 feet x 2.5 Feet Note: 02 No's are required

Welcome

То

Electronics and

Communication Engineering

Silver Jubilee Building



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	Other requirements related to	NITT	Supplier
	the equipment	Requirement	commitment
1.	Installation required	Yes	
2.	Warranty (in Month)	12 Months	
3.	Comprehensive AMC required	No	
4.	Delivery Period (Weeks)	1 Week	
5.		Shipment terms	At NIT-T
6.	Performa	ance Security in %	3%
7.		Payment Terms	100% Payment after
			satisfactory
			delivery/Installation
8.	EMD	D Amount (2 to 5)%	Rs, 5,000/- (2%)

Signature & Seal of Vendor with Date

Note:

Specification of the Supplier should be given in detail, single word confirmation like Complied / No / same will be treated as non - responsive Bid and summarily rejected.

Proof for the supplier's specification must be enclosed along with the quotations.

(catalogue, brochure, and product website link if any)



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DEPARTMENT OF ECE

<u>Annexure- II</u>

PRICE BID FORMAT FOR BIDDERS

Tender No. & Date : Bidder's Offer No. & Date :

S. No.	Description of item			QT Y	Rate / Qty in Rs. (excludin g GST)	G	Total Value + GST in Rs.		
						SGST	CGST	IGST	
		<u> </u>		Gro	up 1: Foam I	Boards			
	Board Type	Dimension		<u> </u>					
1	Foam Board (Dept.	3.5 Feetx3 Feet		04					
	& Institute Vision &								
	MISSION)								
2	Foom Board (Dont	2 5 East v 2 East		06					
2	PEO's) 3mm	5.5 Feel x 5 Feel		00					
	Thickness								
3	Foam Board (Dept.	3.5 Feet x 3 Feet		02					
•	PSO's)								
	3mm Thickness								
4	Foam Board (Dept.	6 Feet x 4 Feet		06					
	PO's								
	3mm Thickness								
5	Foam Board	18 Inch x 3 Inch		42					
	(Miscellaneous)								
	3mm Thickness	101 1 41 1		10					
6	Foam Board (No	18 Inch x 4 Inch		12					
	cell Phone Use with								
	3mm Thickness								
7	Foam Board (Do's	4 Feet x2 5 Feet		12					
•	and Don'ts)	1100t A2.5 100t		12					
	3mm Thickness								
8	Foam Board (Two-	18 Inch x 6 Inch		06					
	Wheeler, Car								
	Parking.)								
	3mm Thickness								
9	Foam Board (UPS,	18 Inch x 5 inch		25					
	Store room & Power								
	Room.)								
	JIIIII I IIICKIIESS								
10	Foam Board (Office	2 Feet x 1.5 Feet		04					
	Working Hours.	_ 1 000 A 1.0 1 000							
	Rooms No's with								
	arrow symbols)								
	3mm Thickness								



11	Foam Board	2 Feet x 1 5 Feet	12			
1	(Emergency	2100t A 1.5 100t	12			
	Number)					
	3mm Thickness					
12	Foam Board (Rest	24 Inch x 6 Inch	06			
	Rooms with	24 men x 0 men	00			
	directional sign					
	Board)					
	3mm Thickness					
13	Foam Board (List of	5 Feet x 3 Feet	01			
15	Laboratories)	5100 × 5100	01			
	3mm Thickness					
14	Foom Board (Lob	18 Inch v 8 Inch	12		 	
14	in Charge ate.)		15			
	amm Thickness					
15	Form Doord (DI	9 East y 4 East	02			
15	Foam Board (PI	8 Feel X 4 Feel	02			
	Project)					
16	5mm Inickness		10			
16	Foam Board (List of	4 Feet x 3 Feet	13			
	Equipment's details					
	etc.)					
17	3mm Thickness		0.1		 	
17	Foam Board (List of	3 Feet x 2 Feet	01			
	HODs)					
10	3mm Thickness					
18	Foam Board (Lab	5 Feet x 2 Feet	12			
	name in 3					
	Languages)					
	3mm Thickness					
19	Foam Board (Room	6 Inch x 4 Inch	70			
	Number)					
	3mm Thickness					
20	Foam Board (Dept.	15 Feet x 2 Feet	01			
	Name)					
	3mm Thickness					
21	Foam Board (Dept.	4 Feet x 3 Feet	01			
	PhD Scholars					
	Details)					
	3mm Thickness					
22	Price per square					
	feet for frames,					
	Other accessories					
	/ spares etc. as					
	given in scope of					
	supply (Individual					
	Item-wise break-up					
	price shall be					
	attached as an					
	annexure to this					
	price bid format.)					



		Î.	r	T	1	[1	
23	Installation and							
	Commissioning							
	(extra, if any) per							
	Square Feet							
						Sub	o Total	
		Gro	up 2: A	Acrylic	c Boards			
24	Acrylic Base Board	7 Feet x 4 Feet		01				
	(Faculty Detail Main							
	Slot Board)							
	3mm Thickness							
25	Acrylic Board (Slot	24 Inch x 2 Inch		60				
	Fixing Faculty							
	Name type)							
	3mm Thickness							
26	Acrylic Hanging	20 Inch x 5 Inch		40				
	Board (Faculty							
	Name in rooms)							
	3mm Thickness							
27	Acrylic Board with	15 Feet x 4Feet		01				
	Frame (Dept. Name)							
	3mm Thickness							
28	Acrylic Engraving	2 Feet x 1 Feet		03				
	Board (Garden							
	related board etc.)							
20	3mm Thickness							
29	feet for frames							
	laser engraving							
	charges							
	Other accessories							
	/ spares etc. as							
	given in scope of							
	supply (Individual							
	item-wise break-up							
	price shall be							
	attached as an							
	annexure to this							
	price bid format.)							
30	Installation and							
	Commissioning							
	(extra, if any) per							
	Square Feet							
						Sub	o Total	
0.1		Group 3: Refl	ector E	ased	Al Boards			
31	Reflector based Al	5 Feet x 2.5 Feet		02				
	Board (Welcome to							
	Dept. Board)							
20	Drice per course							
52	feet for frames.							



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	Other accessories											
	/ spares etc. as											
	given in scope of											
	supply (Individual											
	item-wise break-up											
	price shall be											
	attached as an											
	annexure to this											
	price bid format.)											
33	Installation and											
	Commissioning											
	(extra, if any) per											
	Square Feet											
							Sub	o Total				
34	Packing & Forwardi	ng charges (extra,	if any)									
35	Freight & Transit ins	surance charges, e	extra, if	any								
36	Total price (delivery	, installation and c	ommis	sionir	ng at NIT-T)							
37	Value of Annual Mai	intenance Contrac	:t									
38	Net cost to be paid	l by NIT-T										
		Grand Total Group 1 + Group2 + Group3										

Signature & Seal of Vendor

Note: The price bid should be submitted only as per the above format. No row shall be left blank. Please indicate NA, in case the item is "Not Applicable". If this format is not used or any column is left blank, then the bid will be rejected.



(TO BE PRINTED IN LETTER PAD OF THE FIRM)

EMD Returning Form

To The Director National Institute of Technology, Tiruchirappalli – 620 015

Sub: Returning EMD amount

Sir / Madam,

Our firm has participated in the tender / quotation enquiry No mentioned below and produced the EMD amount through DD, details of the DD are given below.

Tender / Quotation Reference No	
EMD amount	
DD Number	
DD issued Bank	
Date of DD	

It is requested to return the EMD amount to our firm after completion of the purchase to the below mentioned Bank account.

Account Name	
Bank Account Number	
IFSC code	
Bank	

Signature with Seal and Date



(TO BE PRINTED IN LETTER PAD OF THE FIRM)

Annexure – IV

MANDATE FORM FOR ELECTRONIC FUND TRANSFER/RTGS TRANSFER

Date: / /

То

The Director. National Institute of Technology, Tiruchirappalli - 620 015, Tamil Nadu

Sub : Authorization for release of payment / dues from National Institute of Technology, Tiruchirappalli through Electronic Fund Transfer/RTGS Transfer.

- 1. Name of the Party / Firm / Company / Institute
- 2. Address of the Party
- 3. City_____Pin Code_____

 4. E-Mail_____Mobile No:____
- 5. Permanent Account Number_____
- 6. Particulars of Bank:

Bank Name:	Branch Name:															
PIN Code:	Branch							ch (Cod	e:						
IFS Code:(11 digit alpha numeric code						de)										
Account Type	Savings						Сι	Irrei	nt			C	Cash	n Cr	edit	
Account Number:																

DECLARATION

I hereby declare that the particulars given above are correct and complete. If any transaction delayed and not effected for reasons of incomplete or incorrect information I shall not hold Director, National Institute of Technology Tiruchirappalli responsible. I also undertake to advise any change in the particulars of my account to facilitate updating of records for purpose of credit of amount through NEFT/RTGS Transfer.

Place:_____ Date: _____

Signature & Seal of the Authorized Signatory of the Party